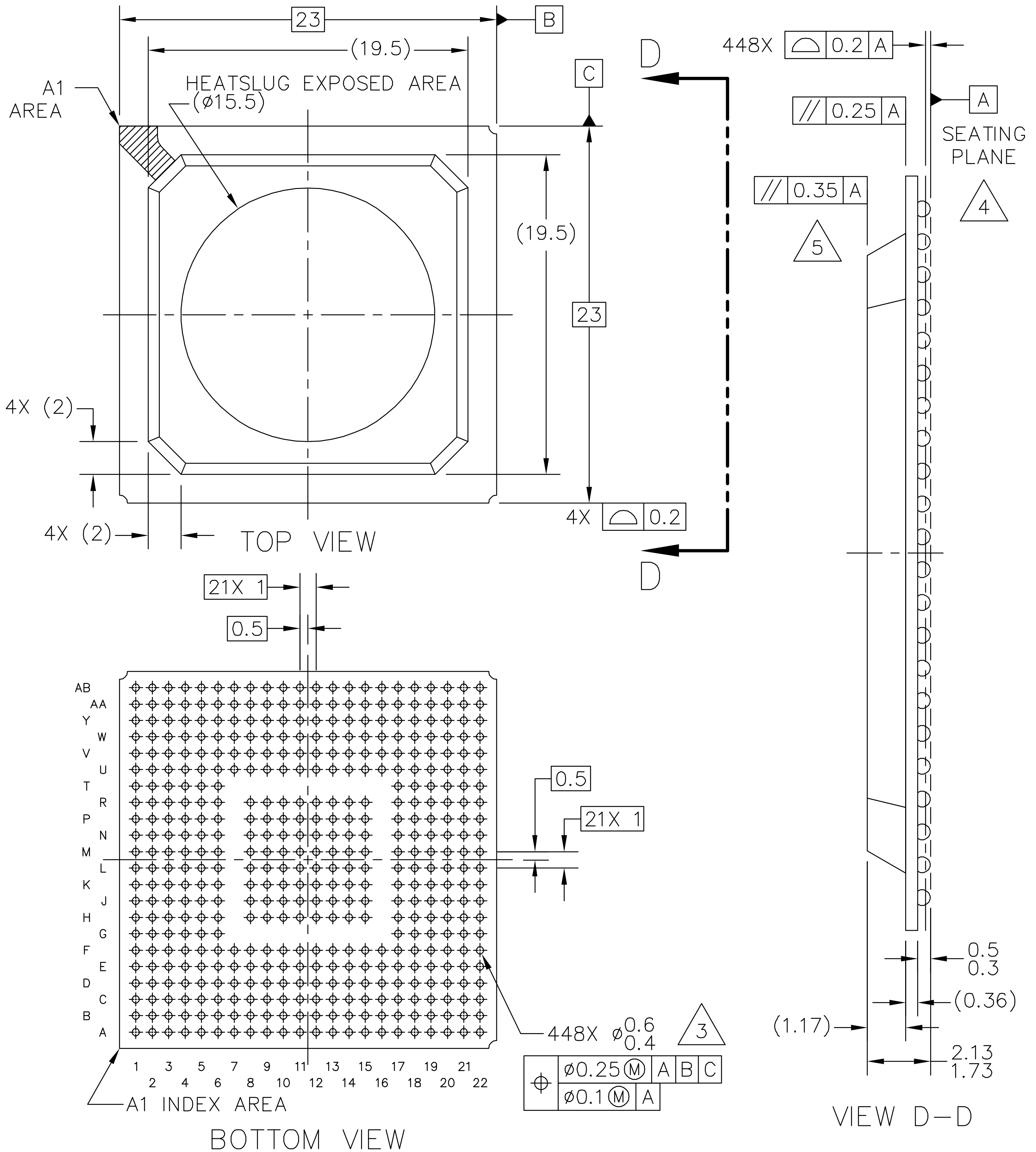

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TITLE: PBGA, WITH HEAT SPREADER, 23 X 23 X 1.93 PKG, 1 MM PITCH, 448 I/O	DOCUMENT NO: 98ASA00747D REV: O
	STANDARD: NON-JEDEC
	21 MAY 2014

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.

2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M–1994.

3. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM A.

4. DATUM A, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

5. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

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